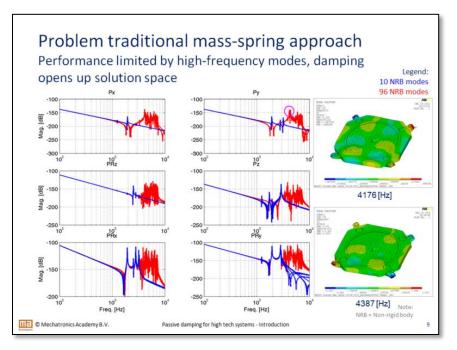
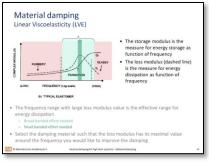
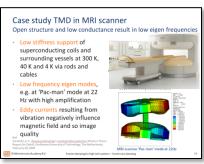
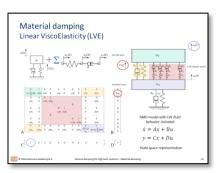
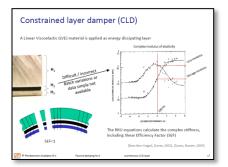
Passive Damping for High Tech Systems



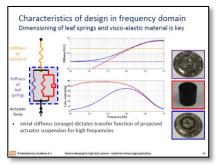


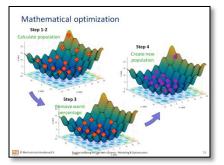


















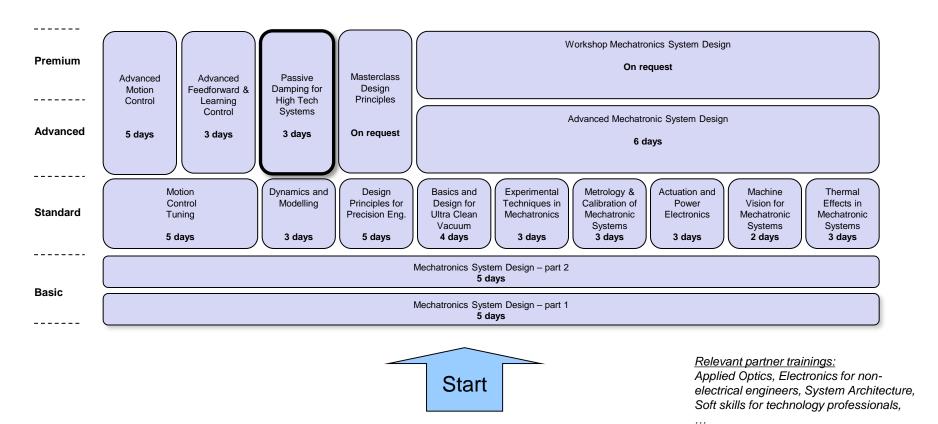
Contents

- Mechatronics Training Curriculum
- Details of Course Passive Damping for High Tech Systems





Mechatronics Training Curriculum



www.mechatronics-academy.nl





Mechatronics Academy

- In the past, many trainings were developed within Philips to train own staff, but the training center CTT stopped.
- Mechatronics Academy B.V. has been setup to provide continuity of the existing trainings and develop new trainings in the field of precision mechatronics. It is founded and run by:
 - Prof. Maarten Steinbuch
 - Prof. Jan van Eijk
 - Dr. Adrian Rankers
- We cooperate in the High Tech Institute consortium that provides sales, marketing and back office functions.





Passive Damping for High Tech Systems





Course Director(s) / Trainers

Teachers

- Prof.Dr.ir. Hans Vermeulen (Eindhoven University of Technology & ASML)
- Dr.ir. Kees Verbaan (NTS Group)

Industrial Guest Speaker

Dr.ir. Stan van der Meulen (ASML)

Course Director(s)

- Prof.Dr.ir. Hans Vermeulen (Eindhoven University of Technology & ASML)
- Dr.ir. A.M. Rankers (Mechatronics Academy)





Program

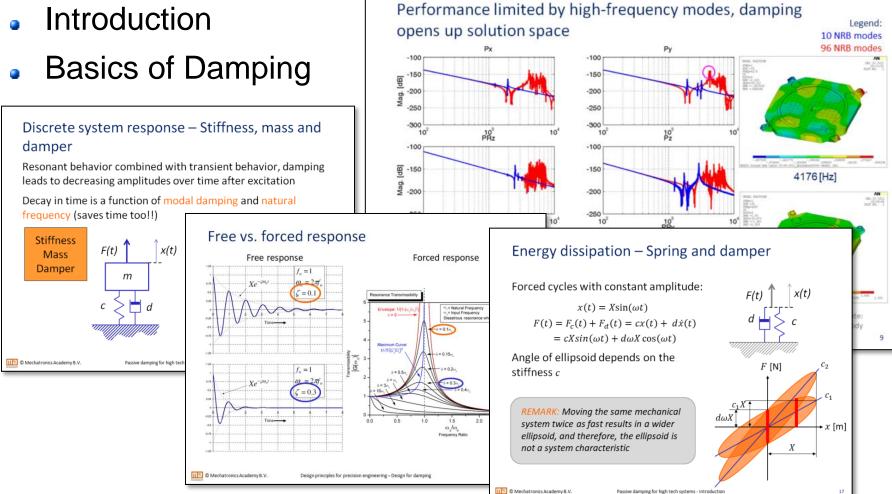
Day	Contents
1	Introduction
	Basics of Damping (energy dissipation, modal damping, exponential decay, other application domains)
	Lunch
	Materials & Damping
	Tuned Mass Dampers (Basics, Design Considerations, Case Study TMD in MRI Scanners)
2	Case TMD Design for Ceramic Tool Slides
	Constrained Layer Damping (Modelling, Case Flexures & Frames)
	Lunch
	Demo & Exercise CLD
	CLD for Discontinuous Surfaces
3	Robust Mass Damping (design, testing & semiconductor wafer stage case)
	Integral Modelling & Optimization (approach, algorithms, over-actuated wafer chuck case)
	Lunch
	Industrial Case Semiconductor Industry (modelling approach, design & analysis)
	Special Topics





Day 1 (morning): Intro & Basics

Introduction



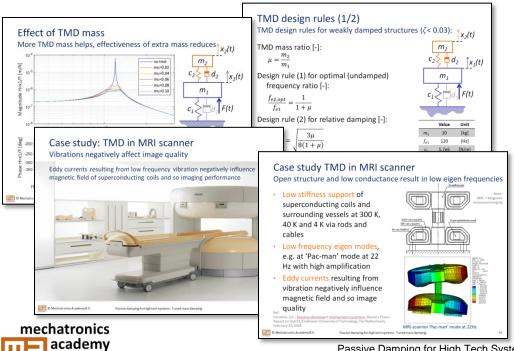
Problem traditional mass-spring approach

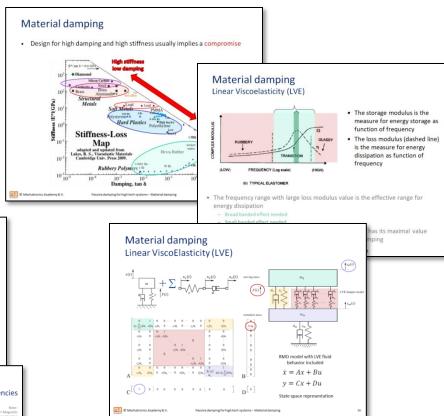
Day 1 (afternoon): Materials & TMD

- Materials & Damping
- Tuned Mass Damping (TMD)
 - Basics

brainport

- Design Considerations
- Case Study MRI Scanner





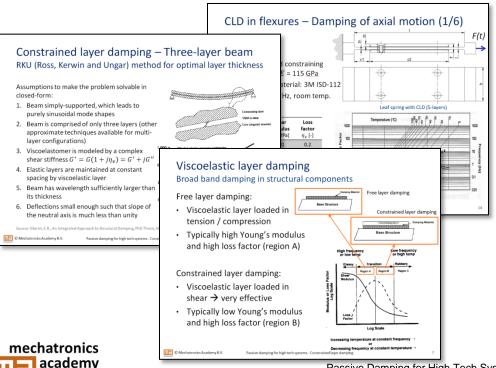


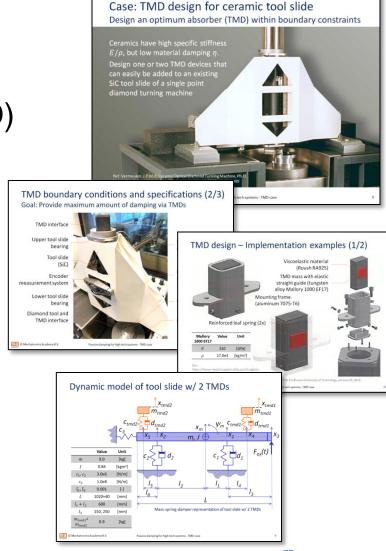
Day 2 (morning): TMD case & CLD

- TMD Case
- Constrained Layer Damping (CLD)
 - Modelling

brainport

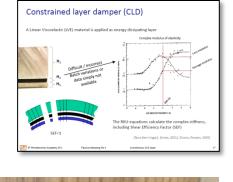
Case Flexures & Frames





Day 2 (afternoon): CLD

- Demo & Exercise CLD
- CLD for Discontinuous Surfaces







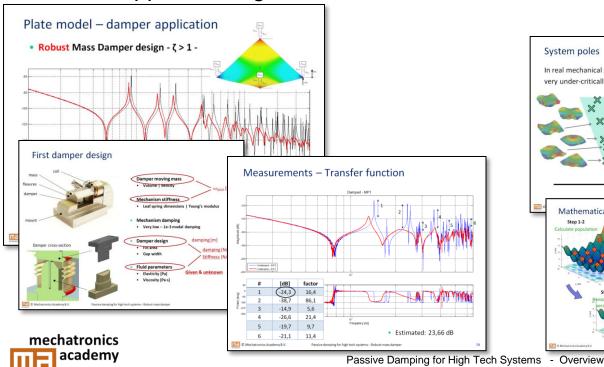


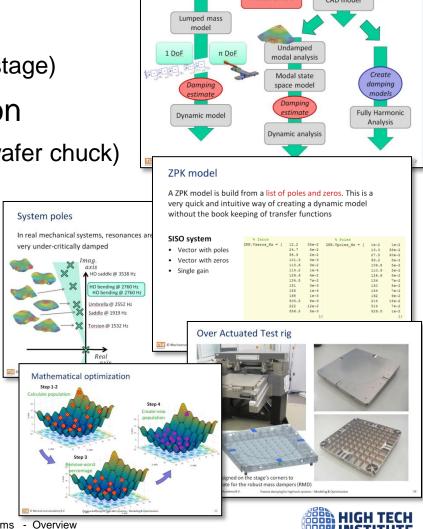


Day 3 (morning): RMD & Modelling

- Robust Mass Damping
 - design, testing, semiconductor wafer stage)
- Integral Modelling & Optimization

approach, algorithms, over-actuated wafer chuck)

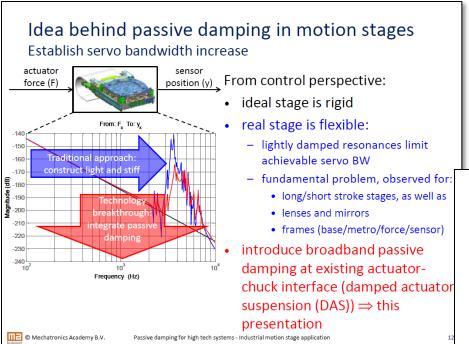




Overview Approaches

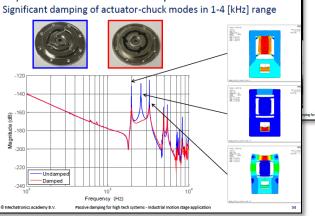
Day 3 (afternoon): Ind. Case & Specials

- Industrial Case 450mm wafer stage
- Special Topics



Design comprises 4 horizontal actuators and 4 position sensors · wafer stage short stroke (WSSS) encoder block (EB) for wafer size transition from 300 to 450 [mm] (0.4% modal damping) 4 horizontal reluctance actuators for in-plane motion (red arrows: x-actuators; green arrows: y-actuators) 4 stage position(ing) measurement (SPM) encoders in square configuration at EB corners (black dots) Modeling of actuator-chuck interface Apply visco-elastic material in parallel to metal leaf springs Characteristics of design in frequency domain Dimensioning of leaf springs and visco-elastic material is key) of creep compensation spring (CCS) f visco-elastic material transfer function Experimental validation on component level Split functionality between force frame and measurement table Radial measurement suspension Experimental validation in system environment

Concept for 450mm lithography





Vibration

isolation table



Sign up for this training

Via the website of our partner High Tech Institute



